

## 1A, 200V - 600V Surface Mount Super Fast Rectifiers

#### **FEATURES**

- Glass passivated junction chip
- Ideal for automated placement
- Super fast recovery time for high efficiency
- Compliant to RoHS Directive 2011/65/EU and in accordance to WEEE 2002/96/EC
- Halogen-free according to IEC 61249-2-21

KEY PARAMETERS					
PARAMETER	VALUE	UNIT			
I <sub>F(AV)</sub>	1	А			
V <sub>RRM</sub>	200-600	V			
I <sub>FSM</sub>	30	А			
$V_F$ at $I_F=1A$	1.7	V			
T <sub>J MAX</sub>	150	°C			
Package	DO-214AC (SMA)				
Configuration	Single dice				

## **APPLICATIONS**

- High frequency rectification
- Freewheeling application
- Switching mode converters and inverters in computer, automotive and telecommunication.

## **MECHANICAL DATA**

- Case: DO-214AC (SMA)
- Molding compound, UL flammability classification rating 94V-0
- Moisture sensitivity level: level 1, per J-STD-020
- Part No. with suffix "H" means AEC-Q101 qualified
- Packing code with suffix "G" means green compound (halogen-free)
- Terminal: Matte tin plated leads, solderable per J-STD-002
- Meet JESD 201 class 2 whisker test
- Polarity: Indicated by cathode band
- Weight: 0.06 g (approximately)





DO-214AC (SMA)

BSOLUTE MAXIMUM RATINGS (T <sub>A</sub> = 25°C unless otherwise noted)					
PARAMETER	SYMBOL	ES1LD	ES1LG	ES1LJ	UNIT
Marking code on the device		ES1LD	ES1LG	ES1LJ	
Maximum repetitive peak reverse voltage	V <sub>RRM</sub>	200	400	600	V
Maximum RMS voltage	V <sub>RMS</sub>	140	280	420	V
Maximum DC blocking voltage	V <sub>DC</sub>	200	400	600	V
Maximum average forward rectified current	I <sub>F(AV)</sub>		1		А
Peak forward surge current, 8.3 ms single half sine-wave superimposed on rated load	I <sub>FSM</sub>		30		А
Operating Junction and Storage Temperature Range	$T_{J}, T_{STG}$	- 55 to +150		°C	



THERMAL PERFORMANCE					
PARAMETER	SYMBOL	LIMIT	UNIT		
Junction to Lead Thermal Resistance	R <sub>ƏJL</sub>	35	°C/W		
Junction to Ambient Thermal Resistance	R <sub>eja</sub>	80	°C/W		
Junction to Case Thermal Resistance	R <sub>eJC</sub>	25	°C/W		

Thermal Performance Note: Units mounted on recommended PCB (16mm x 16mm Cu test board)

<b>ELECTRICAL SPECIFICATIONS</b> (T <sub>A</sub> = 25°C unless otherwise noted)						
PARAMETER		CONDITIONS	SYMBOL	ТҮР	MAX	UNIT
Maximum instantaneous	ES1LD			-	0.95	
forward voltage	ES1LG	_ I <sub>F</sub> = 1A _ T <sub>J</sub> = 25℃	V <sub>F</sub>	I	1.3	V
(Note 1)	ES1LJ			-	1.7	
Maximum reverse current @ rated V <sub>R</sub> (Note 2)		T <sub>J</sub> = 25°C	I <sub>R</sub>	-	5	μA
		T <sub>J</sub> = 125°C		-	100	μA
Junction capacitance	ES1LD	4 8411-	CJ	16	-	pF
	ES1LG	− 1 MHz, − V <sub>R</sub> =4.0V		18		
	ES1LJ	V <sub>R</sub> =4.0V		18		
Reverse recovery time		I <sub>F</sub> =0.5A I <sub>R</sub> =1.0A	t <sub>rr</sub>	-	35	ns
		I <sub>RR</sub> =0.25A				

Notes:

1. Pulse test with PW=0.3 ms

2. Pulse test with PW=30 ms



**ORDERING INFORMATION** 

PART NO.	PART NO. SUFFIX	PACKING Code	PACKING CODE SUFFIX *	PACKAGE	PACKING
		R3			1,800 / 7" Plastic reel
		R2		SMA	7,500 / 13" Paper reel
	Н	M2	G		7,500 / 13" Plastic reel
ES1Lx		F3			1,800 / 7" Plastic reel
(Note 1)		F2		Folded SMA	7,500 / 13" Paper reel
		F4			7,500 / 13" Plastic reel
	N/A E3				1,800 / 7" Plastic reel
			Clip SMA	7,500 / 13" Plastic reel	

Note 1: "x" defines voltage from 200V (ES1LD) to 600V (ES1LJ)

\*: G is optional available.

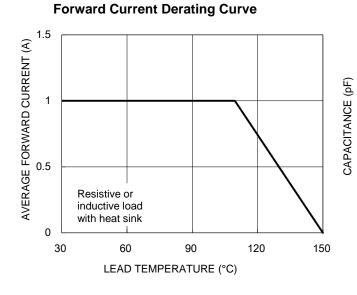
## EXAMPLE:

EXAMPLE P/N	PART NO.	PART NO. SUFFIX	PACKING CODE	PACKING CODE SUFFIX	DESCRIPTION
ES1LDHR3G	ES1LD	н	R3	G	AEC-Q101 qualified Green compound

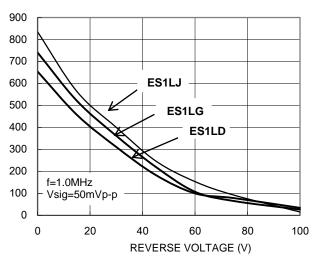


## **CHARACTERISTICS CURVES**

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$ 

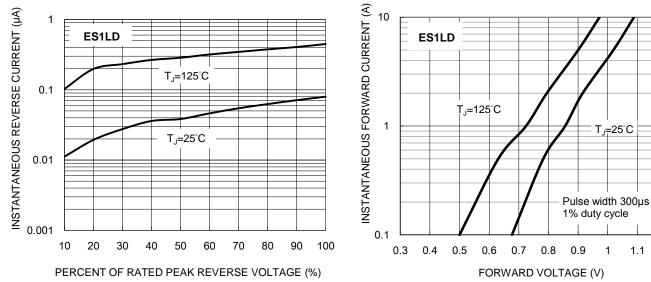


**TYPICAL REVERSE CHARACTERISTICS** 



#### **Typical Junction Capacitance**

## TYPICAL FORWARD CHARACTERISTICS

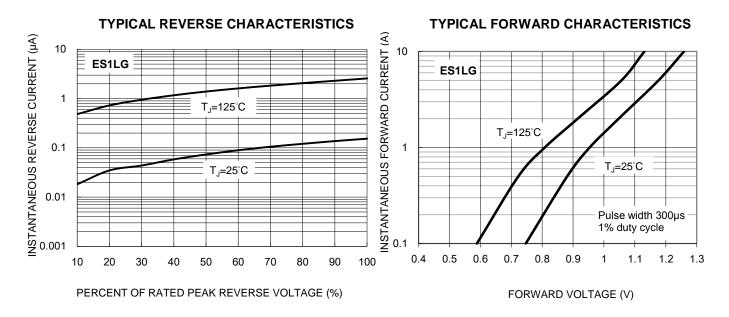


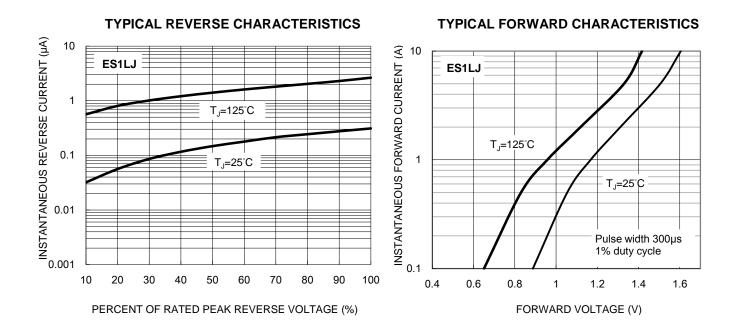
1.2



## **CHARACTERISTICS CURVES**

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$ 



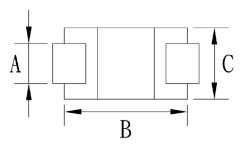


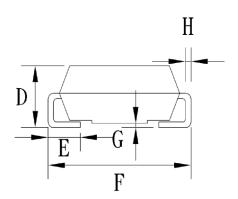


# ES1LD - ES1LJ Taiwan Semiconductor

## PACKAGE OUTLINE DIMENSIONS (Unit: Millimeters)

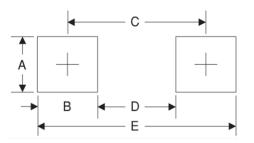
DO-214AC (SMA)





DIM	Unit (mm)		Unit (	(inch)
	Min	Max	Min	Max
A	1.27	1.58	0.050	0.062
В	4.06	4.60	0.160	0.181
С	2.29	2.83	0.090	0.111
D	1.99	2.50	0.078	0.098
E	0.90	1.41	0.035	0.056
F	4.95	5.33	0.195	0.210
G	0.10	0.20	0.004	0.008
н	0.15	0.31	0.006	0.012

## SUGGESTED PAD LAYOUT (Unit: Millimeters)



Symbol	Unit (mm)	Unit (inch)	
А	1.68	0.066	
В	1.52	0.060	
С	3.93	0.155	
D	2.41	0.095	
E	5.45	0.215	

## **MARKING DIAGRAM**



- G = Green Compound
- YW = Date Code
- F = Factory Code



Taiwan Semiconductor

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